



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of: WALLACE

Attorney Docket No.:
SDK1P007/SDK0296.000US

Application No.: 10/039,615

Examiner: Vu, Quang D

Filed: January 4, 2002

Group: 2811

Title: REVERSE WIRE BONDING
TECHNIQUES

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first-class mail on March 17, 2004 in an envelope addressed to the Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450.

Signed: _____

Leslie Russell

**INFORMATION DISCLOSURE STATEMENT
AFTER FINAL ACTION OR NOTICE OF ALLOWANCE
(37 CFR §§ 1.56 AND 1.97(d))**

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

The references listed in the attached PTO Form 1449, a copy of which is attached, may be material to examination of the above-identified patent application. Applicants submit this reference in compliance with their duty of disclosure pursuant to 37 CFR §§1.56 and 1.97. The Examiner is requested to make this citation of official record in this application.

This Information Disclosure Statement is not to be construed as a representation that a search has been made, that additional information material to the examination of this application does not exist, or that this reference indeed constitutes prior art.

This Information Disclosure Statement is being filed after the mailing date of final action under §1.113 or a notice of allowance under §1.311, but before payment of the issue fee.

Accompanying this Information Disclosure Statement is the fee set forth in 37 CFR

1.17(p).

03/23/2004 AWONDAF1 00000085 10039615

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180.00 OP

Enclosed is our Check No. 8800 for \$180.00 in payment of the Information Disclosure Statement Fee. If it is determined that any additional fees are due, the Commissioner is hereby authorized to charge such fees to Deposit Account 500388 (Order No. SDK1P007).

Respectfully submitted,

BEYER WEAVER & THOMAS, LLP

A handwritten signature in dark ink, appearing to read "Phillip P. Lee", followed by a horizontal line.

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Form 1449 (Modified)	Atty Docket No. SDK1P007	Application No.: 10/039,615
Information Disclosure Statement By Applicant	Applicant: WALLACE	
(Use Several Sheets if Necessary)	Filing Date 01/04/2002	Group 2811

U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
	A1						

Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No
	B1							

Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
	C1	John Barber, "Plastic Packaging and the Effects of Surface Mount Soldering Techniques," Microchip Technology, Inc., 12 pages, 1995
	C2	Lai et al., Nordic Electronic Packaging Guideline, Chapter A, printed from: http://www.extra.ivf.se/mgl/A-WireBonding/ChapterA.htm , on March 16, 2004, 25 Pages
	C3	Prof. Daniel F. Baldwin, "Fundamentals of IC Assembly," McGraw-Hill, Chapter. 9, pages 342-353, 2001
	C4	Semiconductor Packaging Assembly Technology, printed from www.national.com , 8 pages, 1999
Examiner		Date Considered

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.